

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	258091	oxid\$5 with (barrier (etch adj stop) tantalum (tantalum adj nitride) titanium molybdenum niobium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 10:44
L2	136	1 with ((reduced reducing minimi\$4 reduce minimizing minimized) near5 conductivity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:52
L3	43	2 and (interconnect\$3 trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:54
L4	2	3 and damascene	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 14:01
L5	75	2 and (interconnect\$3 hole via vias trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:10
L6	32	5 not 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:10
L7	214	1 with ((reduced reducing minimi\$4 reduce minimizing minimized) with conductivity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 10:45
L8	78	7 not 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:15

L9	29	"6249055"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/05/25 09:47
L10	3	"6323553"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/05/25 09:48
L11	24	9 and oxid\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 10:52
L12	0	9 and((reduced reducing minimi\$4 reduce minimizing minimized) with conductivity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 10:45
L13	9	9 and conductivity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 10:46
L14	22194	1 and (((reduced reducing minimi\$4 reduce minimizing minimized) near5 conductivity) (increase\$3 near5 resist\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:54
L15	5243	14 and (interconnect\$3 trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:55
L16	3001	1 same (((reduced reducing minimi\$4 reduce minimizing minimized) near5 conductivity) (increase\$3 near5 resist\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:55
L17	620	16 and (interconnect\$3 trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:56

L18	556	17 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:56
L19	419	18 and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 14:00
L20	4	19 and shunt	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 13:57
L21	348	19 and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 14:00
L22	87	21 and damascene	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 14:26
L23	59	22 and (oxidizing oxidized oxidize)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 17:55
L24	79	22 and (oxygen oxidation oxidizing oxidized oxidize)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 14:43
L25	27	"5913144"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/05/25 16:14
L26	7	23 and (electroless adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:09
L27	0	("2004/0219298").URPN.	USPAT	OR	ON	2005/05/25 18:01

L28	12	24 and (electroless adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:24
L29	5	28 not 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:02
L38	0	jp43008469a	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:18
L40	0	jp4096464a	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:18
L42	0	jp496464a	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:18
L43	18	21 and (electroless adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:30
L44	6	15 and ((cover protect\$3) with surface with (contact interconnect\$3) with (electroless adj plating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:39
L45	9	14 and ((cover protect\$3) with surface with (contact interconnect\$3) with (electroless adj plating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:37

L46	13	15 and ((cover protect\$3) with surface with (electroless adj plating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 18:39
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